

target datasheet

MiniSkiiP@ DUAL 2 650 V / 150 A Features Half-Bridge topology Thereh IGBT and CAL diode chip technology Integrated NTC sensor Solderless spring contact mounting system Schematic Schematic Integrated NTC sensor Solderless spring contact mounting system Schematic Industrial Drive Power Supply Solar UPS Number Supply Solar UPS Sol-M2072PA150SC-K704F40

Maximum Ratings

 $T_{\rm j}$ = 25 °C, unless otherwise specified

| Parameter | Symbol | Condition | Value | Unit | | | |
|-----------------------------------|------------------------------------|---|----------|---------|--|--|--|
| Half-Bridge Switch | | | | | | | |
| Collector-emitter voltage | VCES | | 650 | V | | | |
| Collector current | Ι _C | $T_{\rm j} = T_{\rm jmax}$ $T_{\rm s} = 80 \ ^{\circ}{\rm C}$ | 146 | А | | | |
| Repetitive peak collector current | I crm | $t_{ m p}$ limited by $T_{ m jmax}$ | 450 | А | | | |
| Total power dissipation | P _{tot} | $T_{\rm j} = T_{\rm jmax}$ $T_{\rm s} = 80 \ ^{\circ}{\rm C}$ | 288 | W | | | |
| Gate-emitter voltage | V _{GES} | | ±20 | V | | | |
| Short circuit ratings | t _{SC} V _{CC} | $T_{i} \leq 150 \text{ °C}$ $V_{GE} = 15 \text{ V}$ | 6 360 | μs V | | | |
| Maximum junction temperature | $T_{ m jmax}$ | | 175 | °C | | | |



Maximum Ratings

 $T_{\rm j}$ = 25 °C, unless otherwise specified

| Parameter | Symbol | Conditi | on | Value | Unit | | |
|---|-------------------|----------------------------|-------------------------------|-------------------------------------|------|--|--|
| Half-Bridge Diode | | | | | | | |
| Peak repetitive reverse voltage | $V_{\rm RRM}$ | | | 650 | v | | |
| Continuous (direct) forward current | I _F | $T_{\rm j} = T_{\rm jmax}$ | <i>T</i> _s = 80 °C | 118 | А | | |
| Total power dissipation | P _{tot} | $T_{\rm j} = T_{\rm jmax}$ | <i>T</i> _s = 80 °C | 211 | w | | |
| Maximum junction temperature | $T_{ m jmax}$ | | | 175 | °C | | |
| Module Properties | | | · | | • | | |
| Thermal Properties | | | | | | | |
| Storage temperature | $T_{\rm stg}$ | | | -40+125 | °C | | |
| Operation temperature under switching condition | $T_{ m jop}$ | | | -40(<i>T</i> _{jmax} - 25) | °C | | |
| Isolation Properties | | | | | | | |
| Isolation voltage | V _{isol} | DC Test Voltage | $t_{\rm p}$ = 2 s | 4000 | V | | |
| Creepage distance | | | | min. 12,7 | mm | | |
| Clearance | | | | min. 12,7 | mm | | |
| Comparative Tracking Index | СТІ | | | > 200 | | | |



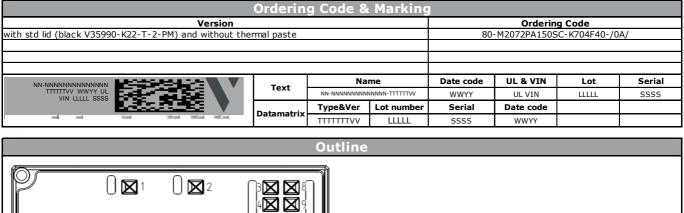
Characteristic Values

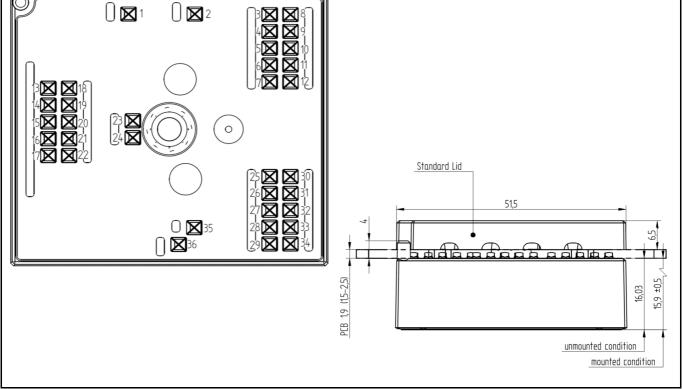
| Parameter | Symbol | Conditions | | | | | Value | | | Unit |
|--------------------------------------|-----------------------|--|--|--|--|-----------------|-------|--------------|--------------|------|
| | | | V _{GE} [V] V _{GS} [V] | $V_{CE} \begin{bmatrix} \mathbf{V} \end{bmatrix}$ $V_{DS} \begin{bmatrix} \mathbf{V} \end{bmatrix}$ $V_{F} \begin{bmatrix} \mathbf{V} \end{bmatrix}$ | I _C [A] I _D [A] I _F [A] | <i>T</i> j [°C] | Min | Тур | Max | |
| Half-Bridge Switch | | | | | | | | | | |
| Static | | | | | | | | | | |
| Gate-emitter threshold voltage | $V_{ m GE(th)}$ | $V_{\rm GE} = V_{\rm CE}$ | | | 0,008 | 25 | 5,1 | 5,8 | 6,4 | V |
| Collector-emitter saturation voltage | V _{CEsat} | | 15 | | 150 | 25 | 0,93 | 1,45 | 1,77 | V |
| Collector-emitter cut-off current | ICES | | 0 | 650 | | 25 | | | 7,6 | μA |
| Gate-emitter leakage current | Iges | | 20 | 0 | | 25 | | | 1200 | nA |
| Internal gate resistance | r _g | | | | | | | 2 | | Ω |
| Input capacitance | Cies | | | 25 | | 25 | | 9240 | | pF |
| Reverse transfer capacitance | Cres | <i>f</i> = 1 MHz | 0 | | | | | 274 | | |
| Thermal | | | 1 | 1 | | | | | 1 | |
| Thermal resistance junction to sink | $R_{ m th(j-s)}$ | Thermal grease thickness \leq 50 µm $\lambda = 1$ W/mK | | | | | | 0,33 | | K/W |
| Half-Bridge Diode | | | • | | | | | | | |
| Static | | | | | | | | | | |
| Forward voltage | $V_{\rm F}$ | | | | 78 | 25 150 | | 1,30 1,24 | 1,62 | V |
| Reverse leakage current | I _R | | | 650 | | 25 150 | | , | 120 40000 | μA |
| Thermal | | | 1 | | | | | l | | |
| Thermal resistance junction to sink | $R_{ m th(j-s)}$ | Thermal grease thickness \leq 50 µm $\lambda = 1$ W/mK | | | | | | 0,45 | | K/W |
| Thermistor | | | | | | | | | | |
| Rated resistance | R | | | | | 25 | | 5 | | kΩ |
| Deviation of R100 | $\Delta_{\rm R/R}$ | $R_{100} = 493 \ \Omega$ | | | | 100 | -5 | | +5 | % |
| Power dissipation | Р | | | | | 25 | | 245 | | mW |
| Power dissipation constant | | | | | | 25 | | 1,4 | | mW/K |
| B-value | B _(25/50) | Tol. ±2 % | | | | 25 | | 3375 | | к |
| B-value | B _(25/100) | Tol. ±2 % | | | | 25 | | 3437 | | к |
| Vincotech NTC Reference | | | | | | | | | К | |



80-M2072PA150SC-K704F40

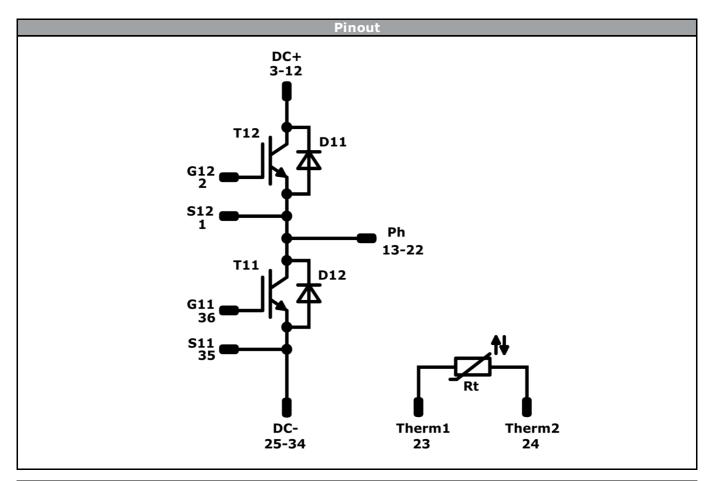
target datasheet







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| Identification | | | | | | |
|----------------|------------|---------|---------|--------------------|---------|--|
| ID | Component | Voltage | Current | Function | Comment | |
| T11, T12 | IGBT | 650 V | 150 A | Half-Bridge Switch | | |
| D11, D12 | FWD | 650 V | 100 A | Half-Bridge Diode | | |
| Rt | Thermistor | | | Thermistor | | |

UL recognition and file number

Standard

>SPQ

This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

| Document No.: | Date: | Modification: | Pages |
|-------------------------------|--------------|---------------|-------|
| 80-M2072PA150SC-K704F40-T1-14 | 18 Apr. 2016 | | |

| | Product status definition | | | | | |
|------------------|---------------------------|--|--|--|--|--|
| Datasheet Status | Product Status | Definition | | | | |
| Target | Formative or In Design | This datasheet contains the design specifications for product development. Specifications may change in any manner without notice. The data contained is exclusively intended for technically trained staff. | | | | |

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target datasheet

Sample

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Handling instruction

Handling instructions for MiniSkiiP[®] 2 packages see vincotech.com website.

Package data

Packaging instruction

Package data for MiniSkiiP[®] 2 Dual packages see vincotech.com website.



Standard packaging quantity (SPQ) 72